

ABSTRACT OF THE DISCLOSURE

5 A liquid thermal management socket system for thermally managing an
6 electronic device in a socket. The liquid thermal management socket system includes
7 a thermal management unit having a chamber for receiving one or more electronic
8 devices, a plurality of first connectors within the thermal management unit for
9 electrically coupling with the electronic device, and a plurality of second connectors
10 electrically coupled to the first connectors, wherein the second connectors extend from
11 the thermal management unit for electrically coupling within a socket unit on a board.
12 The thermal management unit may have a cap member attachable to a base portion in a
13 sealed manner. The chamber within the thermal management unit may thermally
14 manage an electronic device within via spray cooling, liquid immersion or other liquid
15 cooling method.